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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Applicant

Confirmation No.:

Stevens, et al.

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(Use several sheets if necessary)

Filing Date

Group

Examiner Unknown

January 28, 2002

1763

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*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date Appropriate
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	A10	5,674,787	10-07-1997	Zhao, et al.	437	230	01-16-1996
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Date Considered

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.